

Lithium Ion Charge Management IC with Integrated Switching Controller

Features

- ➤ Safe charge of Li-Ion battery packs
- ➤ Pulse-width modulation control for current and voltage regulation
- ➤ Programmable high-side/low-side current-sense
- ➤ Fast charge terminated by selectable minimum current; safety backup termination at maximum time
- ➤ Pre-charge qualification detects shorted or damaged cells and conditions battery
- ➤ Charging continuously qualified by temperature and voltage limits
- ➤ Direct LED control outputs to display charge status and fault conditions

General Description

The bq2954 Li-Ion Charge-Management IC uses a flexible pulse-width modulation regulator to control voltage and current during charging. The regulator frequency is set by an external capacitor for design flexibility. The switch-mode design minimizes power dissipation.

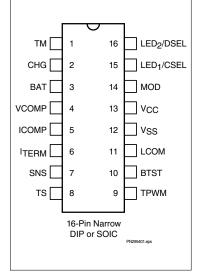
For safety, the bq2954 inhibits fast charging until the battery voltage and temperature are within configured limits. If the battery voltage is less than the low-voltage threshold, the bq2954 provides low-current conditioning of the battery.

For charge qualification, the bq2954 uses an external thermistor to measure battery temperature. Charging begins when power is applied or the battery is inserted

The bq2954 charges a battery in two phases. First a constant-current phase replenishes approximately 70% of battery capacity. Then a voltage-regulation phase completes the battery charge.

The bq2954 provides status indications of all charger states and faults for accurate determination of the battery and charge-system conditions.

Pin Connections



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Pin Names

TM	Time-out programming	TPWM	Regulator timebase input	
	input	BTST	Battery test output	
CHG	Charge active output	LCOM	Common LED output	
BAT	Battery voltage input	V_{SS}	System ground	
VCOMP	Voltage loop comp input	VCC	5.0V±10% power	
ICOMP	Current loop comp input	MOD	Modulation control	
I _{TERM}	Minimum current	MOD	output	
	termination select input	LED ₁ /	Charge status output 1/	
SNS	Sense resistor input	CSEL	Charge sense select input	
TS	Temperature sense input	LED ₂ / DSEL	Charge status output 2/ Display select input	

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Pin De	scriptions	TPWM	Regulation timebase input	
TM	Time-out programming input		Uses an external timing capacitor to ground to set the pulse-width modulation (PWM) frequency. See Equation 7.	
	Sets the maximum charge time. The resistor and capacitor values are determined using	BTST	Battery test output	
	Equation 5. Figure 10 shows the resistor/capacitor connection.		Driven high in the absence of a battery in or-	
CHG	Charge active output		der to provide a potential at the battery terminal when no battery is present.	
	An open-drain output is driven low when the battery is removed, during a temperature	LCOM	Common LED output	
	pend, when a fault condition is present, or when charge is done. CHG can be used to disable a high-value load capacitor to detect quickly any battery removal.		Common output for LED ₁₋₂ . This output is in a high-impedance state during initialization to read programming input on DSEL and CSEL.	
BAT	Battery voltage input	$\mathbf{v_{ss}}$	Ground	
	Sense input. This potential is generally de-	$\mathbf{v}_{\mathbf{CC}}$	$ m V_{CC}$ supply	
	veloped using a high-impedance resistor di- vider network connected between the posi-		5.0V, ±10%	
	tive and the negative terminals of the battery. See Figures 6 and 7 and Equation 1.	MOD	Current-switching control output	
VCOMP	Voltage loop compensation input		Pulse-width modulated push/pull output used to control the charging current to the battery.	
	Connects to an external R-C network to stabilize the regulated voltage.		MOD switches high to enable current flow and low to inhibit current flow. (The maximum duty cycle is 80%.)	
ICOMP	Current loop compensation input	LED ₁ -	Charger display status 1–2 outputs	
	Connects to an external R-C network to stabilize the regulated current.	LED ₂	Drivers for the direct drive of the LED dis-	
ITERM	Charge full and minimum current termination select		play. These outputs are tri-stated during initialization so that DSEL and CSEL can be read.	
	Three-state input is used to set I_{FULL} and I_{MIN} for fast charge termination. See Table 4.	DSEL	Display select input (shared pin with LED_2)	
SNS	Charging current sense input		Three-level input that controls the LED ₁₋₂	
	Battery current is sensed via the voltage developed on this pin by an external sense-resistor.	CSEL	charge display modes.	
TS	Temperature sense input	CSEL	Charge sense-select input (shared pin with LED ₁)	
	Used to monitor battery temperature. An external resistor-divider network sets the lower and upper temperature thresholds. (See Figures 8 and 9 and Equations 3 and 4.)		Input that controls whether current is sensed on low side of battery or high side of battery. A current mirror is required for high-side sense.	

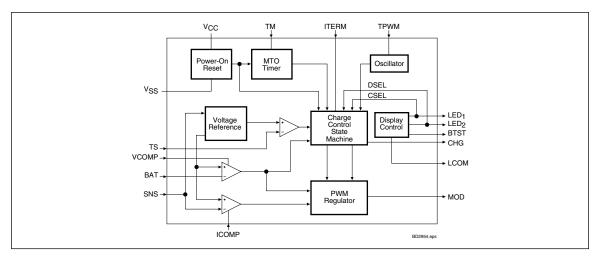


Figure 1. Functional Block Diagram

Functional Description

The bq2954 functional operation is described in terms of the following (Figure 1):

- Charge algorithm
- Charge qualification
- Charge status display
- Configuring the display and termination
- Voltage and current monitoring
- Battery insertion and removal
- Temperature monitoring
- Maximum time--out
- Charge regulation
- Recharge after fast charge

Charge Algorithm

The bq2954 uses a two-phase fast-charge algorithm. In phase 1, the bq2954 regulates constant current until the voltage on the BAT pin, VBAT, rises to the internal threshold, VREG. The bq2954 then transitions to phase 2 and regulates constant voltage (VBAT = VREG) until the charging current falls below the programmed IMIN threshold. Fast charge then terminates, and the bq2954 enters the Charge Complete state. (See Figure 2.)

Charge Qualification

The bq2954 starts a charge cycle when power is applied while a battery is present or when a battery is inserted. Figure 2 shows the state diagram for the bq2954. The bq2954 first checks that the battery temperature is within the allowed, user-configurable range. If the temperature is out of range, the bq2954 remains in the QUALIFICATION state (S01) and waits until the battery temperature and voltage are within the allowed range.

If during any state of charge, a temperature excursion occurs HOT, the bq2954 proceeds to the DONE state (S04) and indicates this state on the LED outputs and provides no current. If this occurs, the bq2954 remains in the DONE state unless the following two conditions are met:

- Temperature falls within valid charge range
- VBAT falls below the internal threshold, VRCHG

If these two conditions are met, a new charge cycle begins. During any state of charge, if a temperature excursion occurs COLD, the bq2954 terminates charge and returns to the QUALIFICATION state (S01). Charge restarts if V_{BAT} and temperature are in valid range.

When the temperature and voltage are valid, the bq2954 enters the CONDITIONING state (S02) and regulates current to ICOND (=IMAX/10). After an initial holdoff period tHO (which prevents the IC from reacting to transient voltage spikes that may occur when charge current is first applied), the IC begins monitoring VBAT. If VBAT does not rise to at least $V_{\rm MIN}$ before the expiration of

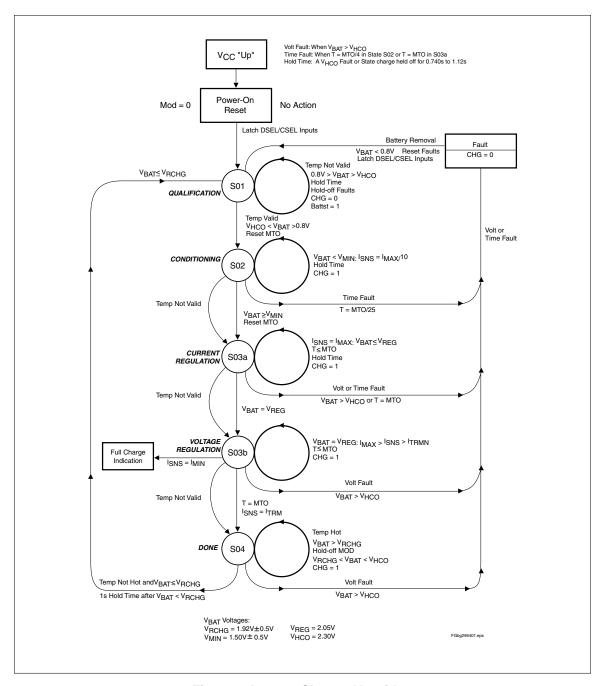


Figure 2. bq2954 Charge Algorithm

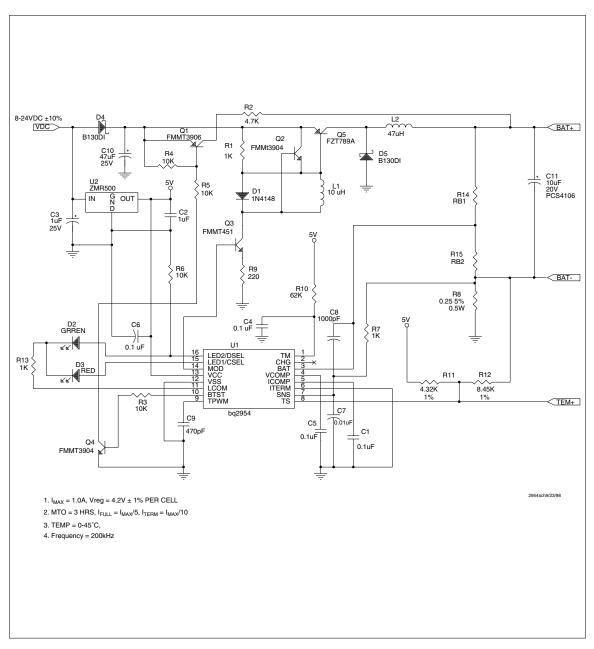


Figure 3. High-Efficiency Li-lon Charger for 1-4 Cells

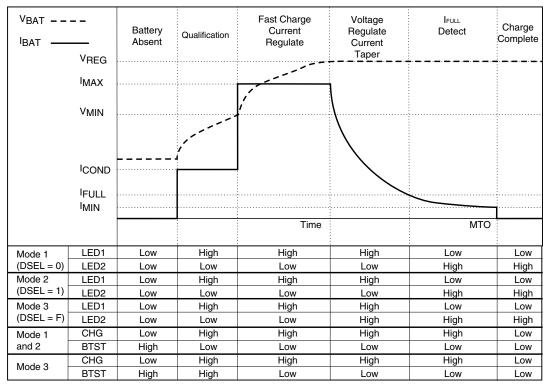


Table 1. Normal Fast Charge Cycle

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time-out limit t_{QT} (i.e., the battery has failed short), the bq2954 enters the Fault state. Then t_{QT} is set to 25% of t_{MTO} . If V_{MIN} is achieved before expiration of the time limit, the bq2954 begins fast charging.

Once in the Fault state, the bq2954 waits until $V_{\rm CC}$ is cycled or a new battery insertion is detected. It then starts a new charge cycle and begins the qualification process again.

Charge Status Display

Charge status is indicated by the LED driver outputs LED_1-LED_2 . Three display modes (Tables 1-3) are available in the bq2954 and are selected by configuring pin DSEL. Table 1 illustrates a normal fast charge cycle, Table 2 a recharge-after-fast-charge cycle, and Table 3 an abnormal condition.

Configuring the Display Mode, I_{FULL}/I_{MIN}, and I_{SENSE}

DSEL/LED₂ and CSEL/LED₁ are bi-directional pins with two functions: as LED driver pins (output) and as programming pins (input). The selection of pull-up, pull-down, or no-resistor programs the display mode on DSEL as shown in Tables 1 through 3. A pull-down or no-resistor programs the current-sense mode on CSEL.

The bq2954 latches the programming data sensed on the DSEL and CSEL input when $V_{\rm CC}$ rises to a valid level. The LEDs go blank for approximately 400ms (typical) while new programming data are latched.

When fast charge reaches a condition where the charging current drops below IFULL, the LED1 and LED2 outputs indicate a full-battery condition. Fast charge terminates when the charging current drops below the

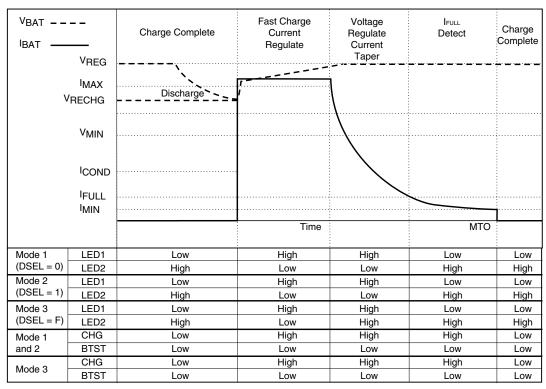


Table 2. Recharge After Fast Charge Cycle

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VBAT ----Battery Qualification Abnormal IBAT -Absent Battery **VREG** $\mathsf{I}_{\mathsf{MAX}}$ $V_{\mbox{\footnotesize{MIN}}}$ **ICOND** IMIN Time tQT Mode 1 LED1 Low High Flash (DSEL = 0) LED2 Low Low Low LED1 Mode 2 Low High Low (DSEL = 1) LED2 Low Low Low Mode 3 LED1 Low High Low (DSEL = F)LED2 Low Low Low CHG Low High Low BTST High Low Low

Table 3. Abnormal Condition

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Table 4. I_{FULL} and I_{MIN} Thresholds

ITERM	I FULL	I _{MIN}
0	I _{MAX} /5	I _{MAX} /10
1	I _{MAX} /10	I _{MAX} /15
Z	I _{MAX} /15	I _{MAX} /20

minimum current threshold, I_{MIN} . The I_{FULL} and I_{MIN} thresholds are programmed using the I_{TERM} input pin (See Table 4.)

Figures 4 and 5 show the bq2954 configured for display mode 2 and $I_{FULL} = I_{MAX}/5$ while $I_{MIN} = I_{MAX}/10$.

Voltage and Current Monitoring

In low-side current sensing, the bq2954 monitors the battery pack voltage as a differential voltage between BAT and pins. In high-side current sensing, the bq2954 monitors the battery pack voltage as a differential voltage between BAT and VSS pins. This voltage is derived by scaling the battery voltage with a voltage divider. (See Figures 6 and 7.) The resistance of the voltage divider must be high enough to minimize battery drain but low enough to minimize noise susceptibility. RB1 + RB2 is typically between 150k Ω and 1M Ω . The voltage-divider resistors are calculated from the following:

$$\frac{RB1}{RB2} = \frac{N*V_{\rm CELL}}{V_{\rm REG}} - 1 \tag{1} \label{eq:RB1}$$

where

 $\begin{array}{l} V_{CELL} = Manufacturer\text{-specified charging cell voltage} \\ N = Number \ of cells \ in \ series \\ V_{REG} = 2.05 V \end{array}$

The current sense resistor, R_{SNS} (see Figures 6 and 7), determines the fast-charge current. The value of R_{SNS} is given by the following:

$$R_{\rm SNS} = \frac{0.25 V}{I_{\rm MAX}} \tag{2}$$

where I_{MAX} is the current during the constant-current phase of the charge cycle. (See Table 1.)

Battery Insertion and Removal

VBAT is interpreted by the bq2954 to detect the presence or absence of a battery. The bq2954 determines that a battery is present when VBAT is between the High-Voltage Cutoff ($V_{HCO} = V_{REG} + 0.25V$) and the Low-Voltage Cutoff ($V_{LCO} = 0.8V$). When V_{BAT} is outside this range, the bq2954 determines that no battery is present and transitions to the battery test state, testing for valid battery voltage. The bq2954 detects battery removal when VBAT falls below VLCO. The BTST pin is driven high during battery test and can activate an external battery contact pull-up. This pull-up may be used to activate an over-discharged Li-Ion battery pack. The VHCO limit implicitly serves as an over-voltage charge fault. The CHG output can be used to disconnect capacitors from the regulation circuitry in order to quickly detect a battery-removed condition.

Battery insertion is detected within 500ms. Transition to the fast-charge phase, however, will not occur for time $t_{\rm HO}$ (approximately one second), even if voltage qualification $V_{\rm MIN}$ is reached. This delay prevents a voltage spike at the BAT input from causing premature entry into the fast-charge phase. It also creates a delay in detection of battery removal if the battery is removed during this hold-off period.

Temperature Monitoring

Temperature is measured as a differential voltage between TS and BAT-. This voltage is typically generated by a NTC (negative temperature coefficient) thermistor and thermistor linearization network. The bq2954 compares this voltage to its internal threshold voltages to determine if charging is allowed. These thresholds are the following:

- High-Temperature Cutoff Voltage: V_{TCO} = 0.4 * V_{CC}
 This voltage corresponds to the maximum temperature (TCO) at which charging is allowed.
- High-Temperature Fault Voltage: VHTF = 0.44 * VCC
 This voltage corresponds to the temperature (HTF) at which charging resumes after exceeding TCO.
- Low-Temperature Fault Voltage: VLTF = 0.6 * VCC This voltage corresponds to the minimum temperature (LTF) at which charging is allowed.

Charging is inhibited if the temperature is outside the LTF—TCO window. Once the temperature exceeds TCO, it must drop below HTF before charging resumes.

RT1 and RT2 for the thermistor linearization network are determined as follows:

$$0.6 * V_{\rm CC} = \frac{V}{1 + \frac{RT1 * (RT2 + R_{\rm LTF})}{(RT2 * R_{\rm LTF})}} \eqno(3)$$

$$0.44 = \frac{1}{1 + \frac{RT1 * (RT2 + R_{HTF})}{(RT2 * R_{HTF})}} \tag{4}$$

where

RITE = thermistor resistance at LTF

RHTF = thermistor resistance at HTF

 $V = V_{CC}$ - 0.250 in low-side current sensing

 $V = V_{\rm CC}$ in high-side current sensing

TCO is determined by the values of RT1 and RT2. 1% resistors are recommended.

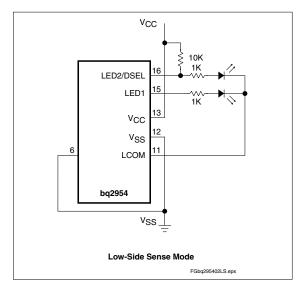


Figure 4. Configured Display Mode (Low-Side Sense)

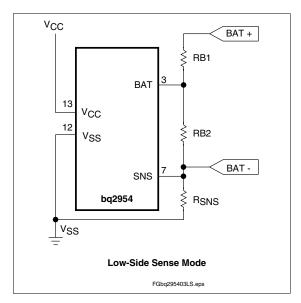


Figure 6. Configuring the Battery Divider (Low-Side Sense)

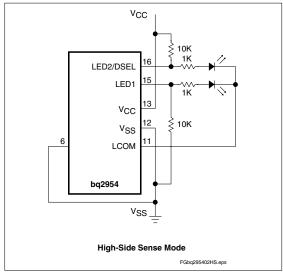


Figure 5. Configured Display Mode (High-Side Sense)

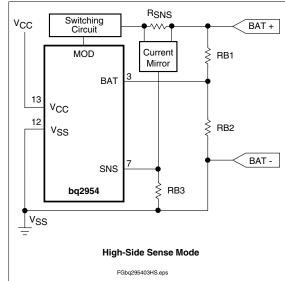


Figure 7. Configuring the Battery Divider (High-Side Sense)

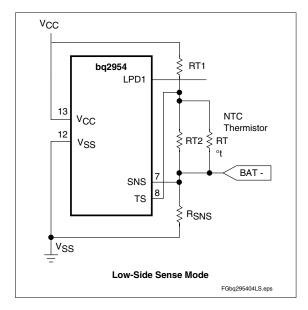


Figure 8. Low-Side Temperature Sensing

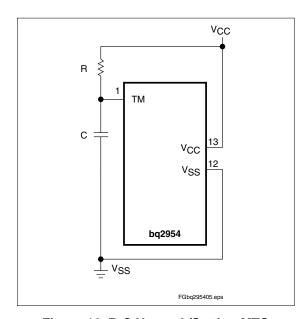


Figure 10. R-C Network/Setting MTO

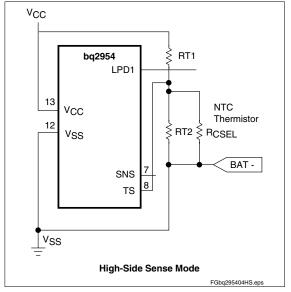


Figure 9. High-Side Temperature Sensing

Disabling Temperature Sensing

Temperature sensing can be disabled by placing a $10k\Omega$ resistor between TS and BAT- and a $10k\Omega$ resistor between TS and V_{CC} . See Figures 8 and 9.

Maximum Time-Out

Maximum Time-Out period (t_{MTO}) is programmed from 1 to 24 hours by an R-C network on the TM pin (see Figure 10) per the following equation:

$$t_{\text{MTO}} = 500 * R * C$$
 (5)

where R is in ohms, C is in Farads, and t_{MTO} is in hours. The recommended value for C is $0.1\mu F_{\cdot}$

The MTO timer is reset at the beginning of fast charge. If the MTO timer expires during the voltage regulation phase, fast charging terminates and the bq2954 enters the Charge Complete state. If the conditioning phase continues for time equal to $t_{\rm QT}$ (MTO/4) and the battery potential does not reach VMIN, the bq2954 enters the fault state and terminates charge. See Table 3. If the MTO timer expires during the current-regulation phase (VBAT never reaches VREG), fast charging is terminated, and the bq2954 enters the fault state.

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Charge Regulation

The bq2954 controls charging through pulse-width modulation of the MOD output pin, supporting both constant-current and constant-voltage regulation. Charge current is monitored at the SNS pin, and charge voltage is monitored at the BAT pin. These voltages are compared to an internal reference, and the MOD output is modulated to maintain the desired value. The maximum duty cycle is 80%.

Voltage at the SNS pin is determined by the value of resistor $R_{\rm SNS}$, so nominal regulated current is set by the following equation:

$$I_{MAX} = V_{SNS} / R_{SNS}$$
 (6)

The switching frequency of the MOD output is determined by an external capacitor (CPWM) between the pin TPWM and $V_{\rm SS}$ pins, per the following:

$$f_{PWM} = \frac{1 * 10^{-4}}{C_{PWM}} \tag{7}$$

Where C is in Farads and the frequency is in Hz. A typical switching rate is 100kHz, implying CPWM = $0.001\mu F$. MOD pulse width is modulated between 0 and 80% of the switching period.

To prevent oscillation in the voltage and current control loops, frequency compensation networks (C and R-C respectively) are typically required on the V_{COMP} and I_{COMP} pins.

Recharge After Fast Charge

Once charge completion occurs, a fast charge is initiated when the battery voltage falls below VRECHG threshold. A delay of approximately one second passes before recharge begins so that adequate time is allowed to detect battery removal. (See Table 1.)

Absolute Maximum Ratings

Symbol	Parameter	Minimum	Maximum	Unit	Notes
$v_{\rm CC}$	V _{CC} relative to V _{SS}	-0.3	+7.0	V	
V_{T}	DC voltage applied on any pin excluding V _{CC} relative to V _{SS}	-0.3	+7.0	V	
m		-20	+70	°C	Commercial
TOPR	Operating ambient temperature	-40	+85	°C	Industrial "N"
T_{STG}	Storage temperature	-55	+125	°C	
TSOLDER	Soldering temperature	-	+260	°C	10s max.

Note:

Permanent device damage may occur if **Absolute Maximum Ratings** are exceeded. Functional operation should be limited to the Recommended DC Operating Conditions detailed in this data sheet. Exposure to conditions beyond the operational limits for extended periods of time may affect device reliability.

DC Thresholds (TA = TOPR; V_{CC} = 5V $\pm 10\%$)

Symbol	Parameter	Rating	Unit	Tolerance	Notes
$V_{ m REG}$	Internal reference voltage	2.05	V	1%	TA = 25°C
TILEG	Temperature coefficient	-0.5	mV/°C	10%	
VLTF	TS maximum threshold	0.6 * V _{CC}	V	±0.03V	Low-temperature fault
V _{HTF}	TS hysteresis threshold	0.44 * V _{CC}	V	±0.03V	High-temperature fault
V _{TCO}	TS minimum threshold	0.4 * VCC	V	±0.03V	Temperature cutoff
$V_{ m HCO}$	High cutoff voltage	$V_{\rm REG}$ + 0.25V	v	±0.03V	
V _{MIN}	Under-voltage threshold at BAT	1.5	V	±0.05V	
$V_{ m RECHG}$	Recharge voltage threshold at BAT	1.92	v	±0.05V	
$V_{\rm LCO}$	Low cutoff voltage	0.8	V	±0.03V	
17	G	0.250	v	10%	I _{MAX}
$V_{ m SNS}$	Current sense at SNS	0.025	v	10%	ICOND

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Recommended DC Operating Conditions (TA = TOPR)

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
v_{cc}	Supply voltage	4.5	5.0	5.5	V	
VTEMP	TS voltage potential	0	-	VCC	V	V _{TS} - V _{SNS}
VBAT	BAT voltage potential	0	-	VCC	V	
I_{CC}	Supply current	-	2	4	mA	Outputs unloaded
	DSEL tri-state open detection	-2	-	2	μA	Note
I_{IZ}	I _{TERM} tri-state open detection	-2		2	μA	
V_{IH}	Logic input high	V _{CC} - 0.3	-	-	V	DSEL, I _{TERM}
$ m V_{IL}$	Logic input low	-	-	$V_{\rm SS}$ + 0.3	V	DSEL, CSEL, ITERM
	LED ₁ , LED ₂ , BTST, output high	V _C C - 0.8	-	-	V	I _{OH} ≤ 10mA
V_{OH}	MOD output high	V _{CC} - 0.8	-	-	V	I _{OH} ≤ 10mA
	LED ₁ , LED ₂ , BTST, output low	-	-	Vss +0.8	V	I _{OL} ≤ 10mA
	MOD output low	-	-	$V_{\rm SS}$ + 0.8	V	I _{OL} ≤ 10mA
v_{OL}	CHG output low	-	-	$V_{\rm SS}$ + 0.8	V	I _{OL} ≤ 5mA, Note 3
	LCOM output low	-	-	$V_{\rm SS}$ + 0.5	V	$I_{OL} \le 30 mA$
	LED ₁ , LED ₂ , BTST, source	-10	-	-	mA	$V_{\mathrm{OH}} = V_{\mathrm{CC}} - 0.5 V$
Іон	MOD source	-5.0	-	-	mA	$V_{OH} = V_{CC} - 0.5V$
	LED ₁ , LED ₂ , BTST, sink	10	-	-	mA	$V_{OL} = V_{SS} + 0.5V$
	MOD sink	5	-	-	mA	$V_{OL} = V_{SS} + 0.8V$
I_{OL}	CHG sink	5	-	-	mA	$V_{OL} = V_{SS} + 0.8V$, Note 3
	LCOM sink	30	-	-	mA	$V_{OL} = V_{SS} + 0.5V$
Ter	DSEL logic input low source	-	-	+30	μA	$V = V_{SS}$ to $V_{SS} + 0.3V$, Note 2
IIL	I _{TERM} logic input low source	-	-	+70	μA	$V = V_{SS}$ to $V_{SS} + 0.3V$
Tvvv	DSEL logic input high source	-30	-	-	μA	$V = V_{\rm CC}$ - 0.3V to $V_{\rm CC}$
I _{IH}	ITERM logic input high source	-70	-	-	μA	$V = V_{\rm CC} - 0.3V$ to $V_{\rm CC}$

Notes:

- 1. All voltages relative to VSS.
- 2. Conditions during initialization after $V_{\rm CC}$ applied.
- 3. SNS = 0V.

Impedance (TA = TOPR; VCC = $5V \pm 10\%$)

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
R_{BATZ}	BAT pin input impedance	50	-	-	$M\Omega$	
RSNSZ	SNS pin input impedance	50	-	-	${ m M}\Omega$	
RTSZ	TS pin input impedance	50	-	-	$M\Omega$	
R _{PROG1}	Soft-programmed pull-up or pull-down resistor value (for programming)	-	-	10	$k\Omega$	DSEL, CSEL
RPROG2	Pull-up or pull-down resistor value	-	-	3	kΩ	ITERM
R _{MTO}	Charge timer resistor	20	-	480	kΩ	

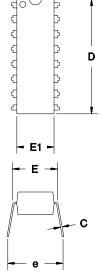
Timing (TA = TOPR; VCC = 5V $\pm 10\%$)

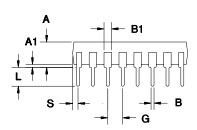
Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
tmto	Charge time-out range	1	-	24	hours	See Figure 10
tQT	Pre-charge qual test time-out period	-	0.25 * tmto	-	-	
tHO	Pre-charge qual test hold-off period	300	600	900	ms	
f _{PWM}	PWM regulator frequency range	-	100	200	kHz	See Equation 7
d _{PWM}	Duty cycle	0	-	80	%	

Capacitance

Symbol	Parameter	Minimum	Typical	Maximum	Unit
Смто	Charge timer capacitor	-	-	0.1	μF
CPWM	PWM capacitor	-	0.001	-	μF

16-Pin DIP Narrow (PN)

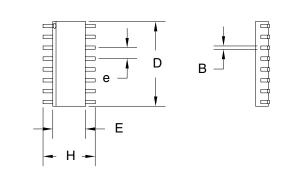


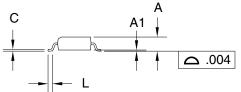


16-Pin PN (0.300" DIP)

	-	-			
	Inc	hes	Millimeters		
Dimension	Min. Max.		Min.	Max.	
A	0.160	0.180	4.06	4.57	
A1	0.015	0.040	0.38	1.02	
В	0.015	0.022	0.38	0.56	
B1	0.055	0.065	1.40	1.65	
C	0.008	0.013	0.20	0.33	
D	0.740	0.770	18.80	19.56	
E	0.300	0.325	7.62	8.26	
E1	0.230	0.280	5.84	7.11	
e	0.300	0.370	7.62	9.40	
G	0.090	0.110	2.29	2.79	
L	0.115	0.150	2.92	3.81	
S	0.020	0.040	0.51	1.02	

16-Pin SOIC Narrow (SN)





16-Pin SN (0.150" SOIC)

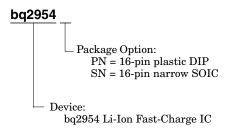
	Inc	hes	Millin	neters
Dimension	Min.	Max.	Min.	Max.
A	0.060	0.070	1.52	1.78
A1	0.004	0.010	0.10	0.25
В	0.013	0.020	0.33	0.51
С	0.007	0.010	0.18	0.25
D	0.385	0.400	9.78	10.16
Е	0.150	0.160	3.81	4.06
e	0.045	0.055	1.14	1.40
Н	0.225	0.245	5.72	6.22
L	0.015	0.035	0.38	0.89

Data Sheet Revision History

Change No.	Page No.	Description of Change
1	All	"Final" changes from "Preliminary" version

Note: Change 1 = Oct. 1998 B changes from Nov. 1997 "Preliminary."

Ordering Information



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking
	, ,				. ,	(4)	(5)		
BQ2954PN	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	2954PN-A3
BQ2954PN.B	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	2954PN-A3
BQ2954PNG4.B	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	2954PN-A3
BQ2954SN	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2954 -A3
BQ2954SN.B	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2954 -A3
BQ2954SNTR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2954 -A3
BQ2954SNTR.B	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2954 -A3
BQ2954SNTR1G4.B	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2954 -A3

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ2954SNTR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
BQ2954SNTR	SOIC	D	16	2500	356.0	356.0	35.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
BQ2954PN	N	PDIP	16	25	506	13.97	11230	4.32
BQ2954PN.B	N	PDIP	16	25	506	13.97	11230	4.32
BQ2954PNG4.B	N	PDIP	16	25	506	13.97	11230	4.32
BQ2954SN	D	SOIC	16	40	506.6	8	3940	4.32
BQ2954SN.B	D	SOIC	16	40	506.6	8	3940	4.32

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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